



**PRINTED CIRCUIT BOARDS**  
**INTERCONNECTION CARRIERS**

State of the Art: PCB's

Revisio

Datum:

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**01**

**4.11.2001**

**1/1**


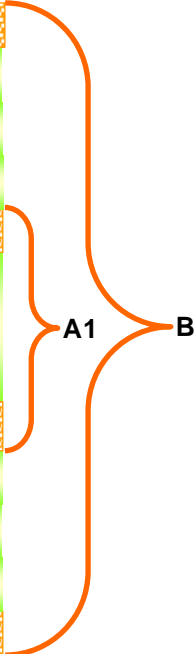
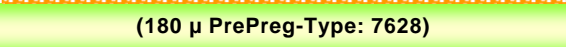


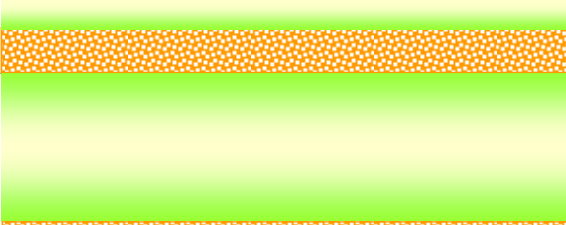





**Schematic Key for Multilayer and HDI-Technology Build-Ups**

a	b	c	d	e	f	g + h + i
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**04 205 FR4 60 L71.70 P18**

columns and equal kind of positions are separated by "\_". Equal prefixes in one column are reduced to one.

**04\_205\_FR4\_60\_L71.70\_p18**

Layers	in $\mu$	Material	Build-Up	Assembly
<b>Layer-1</b>	60 $\mu$	Copper		
	180 $\mu$	Prepreg	(180 $\mu$ PrePreg-Type: 7628)	
	180 $\mu$	Prepreg		
	180 $\mu$	Prepreg		
<b>Layer-2</b>	70 $\mu$	Copper		
	710 $\mu$	L-FR4		
<b>Layer-3</b>	70 $\mu$	Copper		
	180 $\mu$	Prepreg		
	180 $\mu$	Prepreg		
	180 $\mu$	Prepreg		
<b>Layer-99</b>	60 $\mu$	Copper		

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